

Call for Papers - DPS 2025

International Symposium on Dry Process November 13(Thu) - 14(Fri), 2025

The Shiki Museum, Matsuyama, Ehime, Japan

Paper Submission Deadline: July 14, 2025

Author instructions and information about DPS can be found at:

https://www.dry-process.org/2025/





The 46th International Symposium on Dry Process (DPS2025) will be held at the Shiki Museum, Matsuyama, Ehime, Japan from November 13 to 14, 2025. The Symposium covers all aspects of the rapidly evolving fields of dry processes, including but not limited to plasma etching and deposition processes, diagnostics and modeling of plasmas and surfaces, and surface modifications by plasmas, for the applications in, e.g., microelectronics, power devices, sensors, environmental protection, biological systems, and medicine. The DPS has provided valuable forums for in-depth discussion among professionals and students working in this exciting field for more than four decades.

Theme: Dry processes and related technologies from fundamentals to applications

Topics:

- 1. Etching Technologies
- 2. Manufacturing Technologies (AEC, APC, EES, FDC)
- 3. Surface Reaction and Damage
- 4. Plasma Diagnostics and Monitoring Systems
- 5. Computational Approaches (Modeling, Simulation, Machine Learning, Al, Informatics, DX) for Dry Process
- 6. Plasma Generation (Equipment/Source)
- 7. Deposition Technologies (CVD / PVD)
- 8. Atomic Layer Processes (ALD/ALE)
- 9. Dry process for Green Transformation: GX (Energy saving technology, Alternative gas, Sustainability)
- 10. Plasma Processes for New Material Devices (MRAM, Power, Organic, III-V, 2D)
- 11. Plasma Processes for Biological and Medical application, MEMS
- 12. Atmospheric Pressure Plasma and Liquid Plasma
- 13. New Dry Process Concepts
- 14. Dry Processes for 3D-IC / Packaging

Arranged session:

AS1-Understanding the mechanisms for future high-aspect-ratio etching technology AS2-Atomic layer processes (ALE/ALD/ASD) for ultimate control of surface reaction

AS3-Dry process technology for 3D-IC and advanced packaging

For further general information, please contact: e-mail: dps2025@officepolaris.co.j

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